

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = +25^\circ C$
20V	3.0Ω @ $V_{GS} = 4.5V$	240mA
	6.0Ω @ $V_{GS} = 1.8V$	180mA

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions

Features

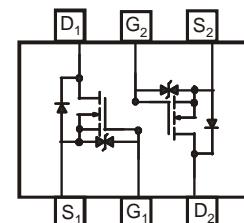
- Dual N-Channel MOSFET
- Low On-Resistance:
 - 3.0Ω @ 4.5V
 - 4.0Ω @ 2.5V
 - 6.0Ω @ 1.8V
 - 10Ω @ 1.5V
- Very Low Gate Threshold Voltage, 1.05V Max
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surface Mount Package
- ESD Protected Gate (HBM 300V)
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SOT963
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.0027 grams (Approximate)



Top View


 Top View
 Schematic and Transistor Diagram

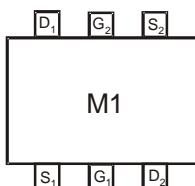
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN26D0UDJ-7	SOT963	10,000/Tape & Reel

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information (Note 5)



M1 = Product Type Marking Code

Note: 5. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	± 10	V
Continuous Drain Current (Note 6) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	240 190	mA
Continuous Drain Current (Note 6) $V_{GS} = 1.8\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	180 140	mA
Pulsed Drain Current - $T_P = 10\mu\text{s}$			I_{DM}	805	mA

Thermal Characteristics

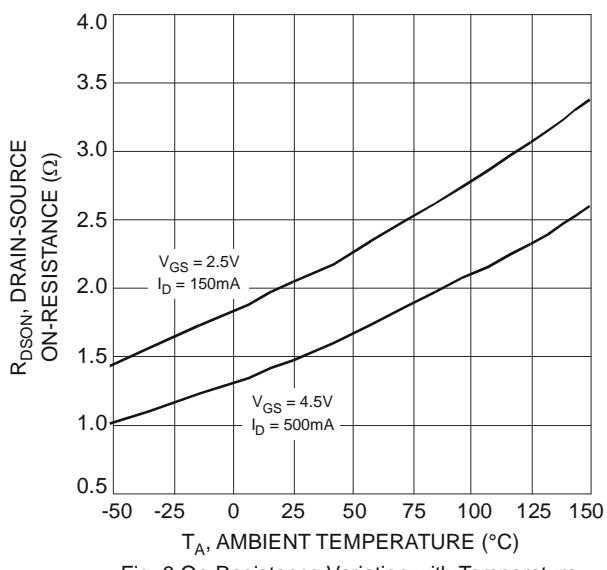
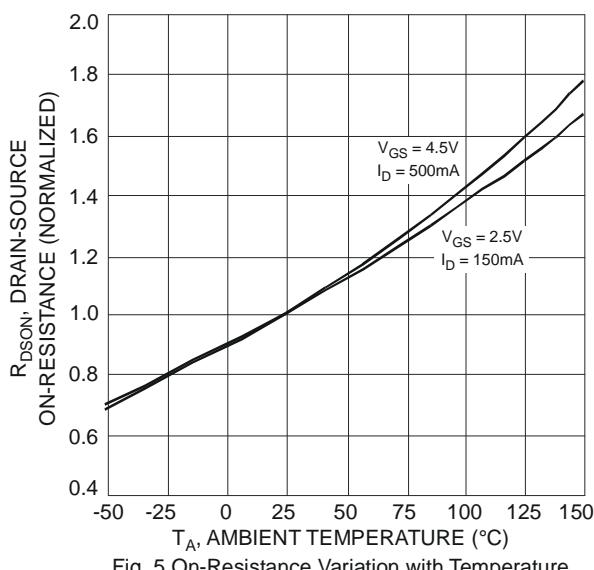
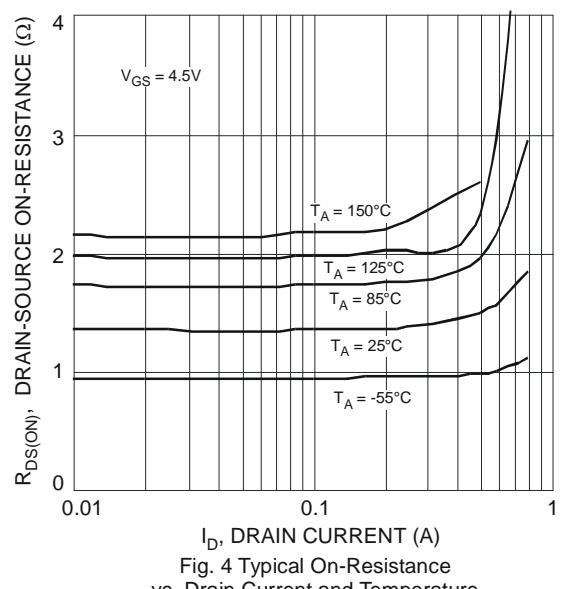
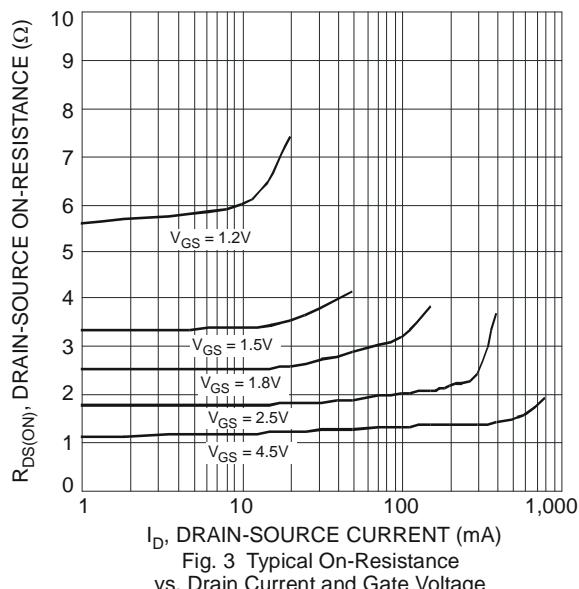
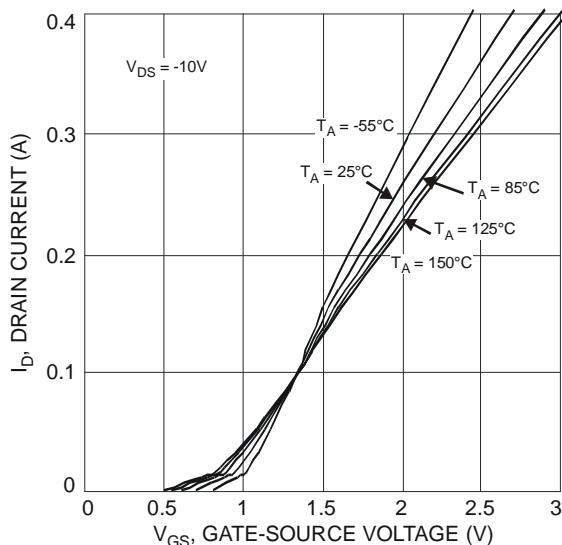
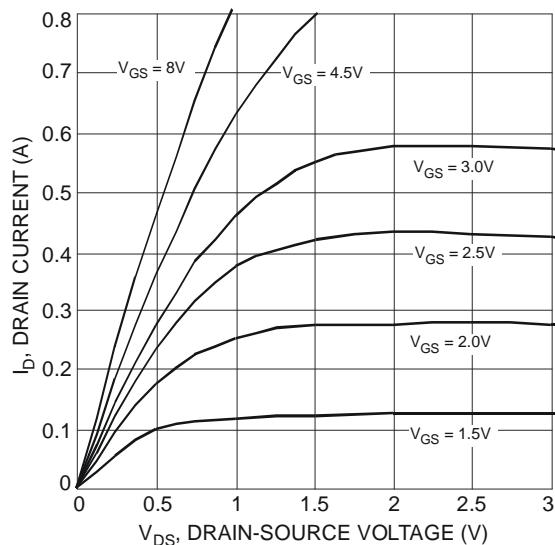
Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P_D	300	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	409	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$V_{GS} = 0\text{V}, I_D = 100\mu\text{A}$
Zero Gate Voltage Drain Current @ $T_J = +25^\circ\text{C}$ @ $T_J = +85^\circ\text{C}$ (Note 8)	I_{DSS}	—	—	500 1.7	nA μA	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 2.6\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage	I_{GSS}	—	—	± 1 ± 100	μA nA	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$ $V_{GS} = \pm 5\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	0.45	0.8	1.05	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	— — — — —	1.8 2.5 3.4 4.7 9.5	3.0 4.0 6.0 10.0 —	Ω	$V_{GS} = 4.5\text{V}, I_D = 100\text{mA}$ $V_{GS} = 2.5\text{V}, I_D = 50\text{mA}$ $V_{GS} = 1.8\text{V}, I_D = 20\text{mA}$ $V_{GS} = 1.5\text{V}, I_D = 10\text{mA}$ $V_{GS} = 1.2\text{V}, I_D = 1\text{mA}$
Forward Transconductance	$ Y_{fs} $	180	240	—	mS	$V_{DS} = 10\text{V}, I_D = 0.1\text{A}$
Source-Drain Diode Forward Voltage	V_{SD}	0.5	0.8	1.0	V	$V_{GS} = 0\text{V}, I_S = 10\text{mA}$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	14.1	—	pF	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	2.9	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	1.6	—	pF	
SWITCHING CHARACTERISTICS, $V_{GS} = 4.5\text{V}$ (Note 8)						
Turn-On Delay Time	$t_{d(on)}$	—	3.8	—	ns	$V_{GS} = 4.5\text{V}, V_{DD} = 10\text{V}$ $I_D = 200\text{mA}, R_G = 2.0\Omega$
Rise Time	t_r	—	7.9	—		
Turn-Off Delay Time	$t_{d(off)}$	—	13.4	—		
Fall Time	t_f	—	15.2	—		

Notes:

6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch with minimum recommended pad layout; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design, not subject to production testing.



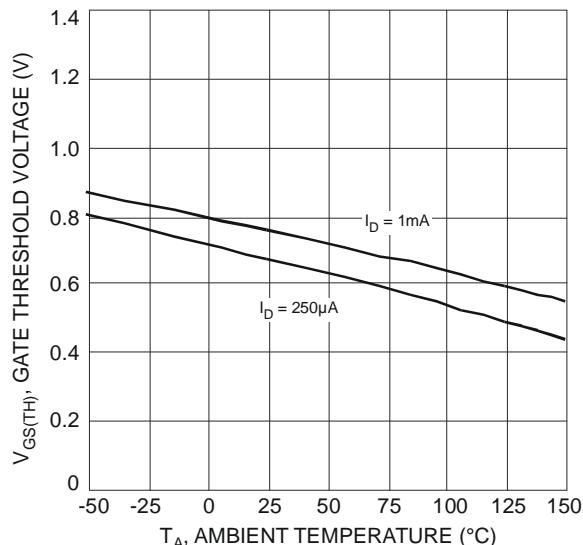


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

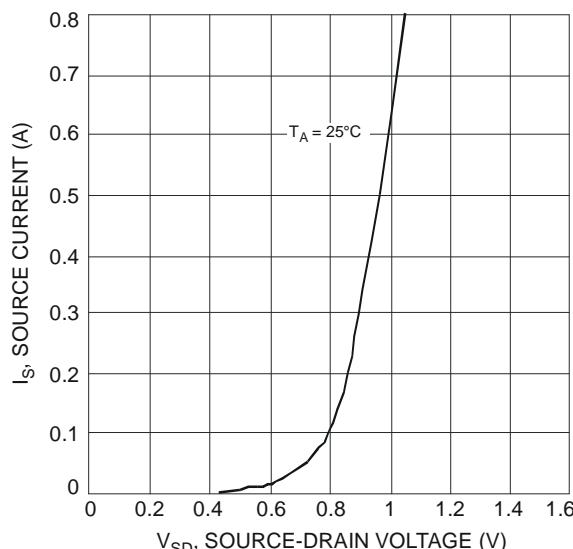


Fig. 8 Diode Forward Voltage vs. Current

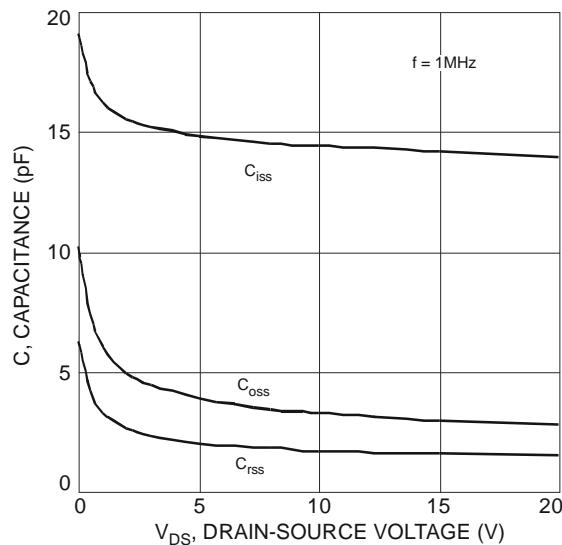


Fig. 9 Typical Total Capacitance

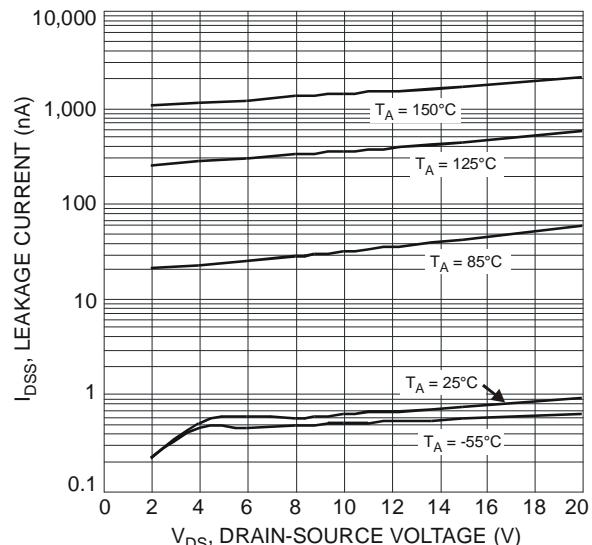
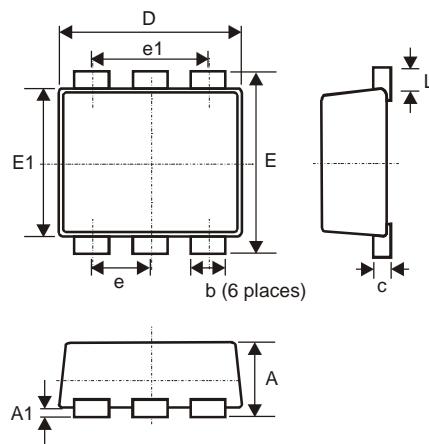


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

Package Outline Dimensions

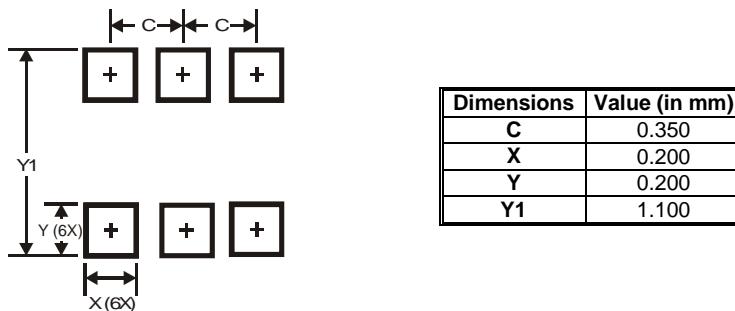
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT963			
Dim	Min	Max	Typ
A	0.40	0.50	0.45
A1	0	0.05	-
c	0.120	0.180	0.150
D	0.95	1.05	1.00
E	0.95	1.05	1.00
E1	0.75	0.85	0.80
L	0.05	0.15	0.10
b	0.10	0.20	0.15
e	0.35 Typ		
e1	0.70 Typ		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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